

P-FTM8-2-1

Ultrathin Wire Bond Mold Package
For contactless application (Controller)

Short Product Overview

May 2010

Chip Card & Security

P-FTM8-2-1 Short Product Overview	Ref.: Chip_Card_Product_Overview_11/09
Revision History: Current Version 05.10	
Previous Releases:	
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Important: Further information is confidential and on request. Please contact:
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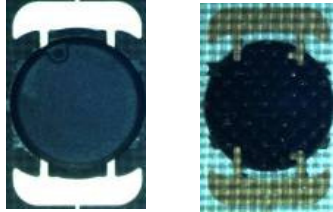
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Product name P-FTM8-2-1	P-FTM8-2-1
Picture	
Product description	2 Antenna Contacts Wire Bond + Mold + Epoxy Tape Controller only
Typical Applications	Government Identification, e-Passport, Driver License
Pitch	9.5mm
Dimensions	8.2 x 5.7mm
Thickness	max. 260µm
Contact Surface	NiAu
Delivery form	Tape on Reel Reel diameter 330mm
ISO - reference	ISO/IEC 7810 SO/IEC 7816-1 ISO/IEC 10373-1 / -3
Derivatives	

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